

Please replace the claims, including all prior versions, with the listing of claims below.

**LISTING OF CLAIMS:**

Claims 1-4 (Canceled)

Claim 5 (Previously presented) A board for a plasma color display on which striped barrier ribs for partitioning address electrodes and discharge spaces are formed and on which phosphor layer stripes emitting red, green and blue light are formed in grooves between the respectively adjacent barrier ribs, wherein two or more phosphor layer stripes emitting light of the same color are formed in respectively adjacent grooves.

Claim 6 (Previously presented) A board for a plasma display according to claim 5, wherein two or more blue light emitting phosphor layer stripes are formed in the respectively adjacent grooves.

Claim 7 (Previously presented) A plasma display, comprising a front glass board having electrodes, a dielectric and a protective film formed on the front glass board and a rear glass board having electrodes, a dielectric, barrier ribs and phosphors formed on the rear glass board, the board for a plasma display according to claim 5 being used as the rear board.

Claim 8 (Previously presented) A process for producing the board for a plasma display according to claim 5, comprising, in order, applying a photosensitive paste over a surface of the board, exposing the photosensitive paste to a barrier rib pattern, developing the exposed photosensitive paste of the board to remove portions dissolved by a developer, and firing the developed board at 450°C to 620°C, so as to form barrier ribs on the board.

Claim 9 (Original) A plasma display, comprising a front glass board having electrodes, a dielectric and a protective film formed on the front glass board and a rear glass board having electrodes, a dielectric, barrier ribs and phosphors formed on the rear glass board, the board for a plasma display according to claim 6 being used as the rear board.

Claim 10 (Original) A process for producing the board for a plasma display according to claim 6, comprising, in order, applying a photosensitive paste over a surface of the board, exposing the photosensitive paste to a barrier rib pattern, developing the exposed photosensitive paste of the board to remove portions dissolved by a developer, and firing the developed board at 450°C to 620°C, so as to form barrier ribs on the board.